## PATENT ASSIGNMENT

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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
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Atsushi SANO	07/01/2010
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Postal Code:	1018980	

Name:	Renesas Electronics Corp.	
Street Address:	1753 Shimonumabe, Nakahara-ku	
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#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12822317

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	1270.110BS	
NAME OF SUBMITTER:	Carl I. Brundidge	
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PATENT REEL: 024802 FRAME: 0028

## ASSIGNMENT

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to the undersigned by Hitachi Kokusai Electric, Inc., a corporation organized under the laws of Japan, located at 14-1 Sotokanda 4chome, Chiyoda-ku, Tokyo 1018980, Japan, and Renesas Electronics Corp., a corporation organized under the laws of Japan, located at 1753 Shimonumabe, Nakahara-ku, Tokyo 1018980, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Kokusai Electric, Inc. and Renesas Electronics Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE AND SUBSTRATE PROCESSING APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Kokusai Electric, Inc. and Renesas Electronics Corp., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made:

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Kokusai Electric, Inc. and Renesas Electronics Corp. and do hereby authorize the Law Firm Brundidge & Stanger, P.C. to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

Date Signed

1) Sadayoshi Horii

2) Atsushi Sano

Atsushi Sano

July 1. 2010 July 1. 2010

PATENT REEL: 024802 FRAME: 0029 3) Masahito Kitamura

Masahito Kitamura

July 1, 2010

4) Yoshitake Kato

Yosh take Kats

July 12, 2010

PATENT

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